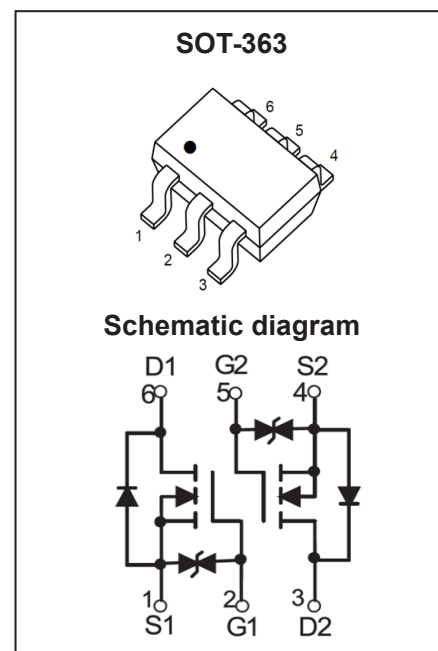


## 20V N- and P- Channel MOSFET

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
20V	170mΩ@4.5V	0.75A
	230mΩ@2.5V	
	330mΩ@1.8V	
-20V	400mΩ@-4.5V	-0.66A
	570mΩ@-2.5V	
	810mΩ@-1.8V	



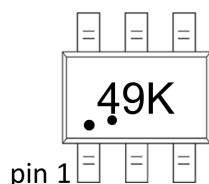
### Feature

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- ESD Protected Gate

### Application

- Load Switch
- DC/DC Converter

### MARKING:



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Value	Unit
Drain - Source Voltage	$V_{DS}$	20	-20	V
Gate - Source Voltage	$V_{GS}$	$\pm 10$	$\pm 10$	V
Continuous Drain Current <sup>1,5</sup>	$I_D$	0.75	-0.66	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	1.8	-1.2	A
Power Dissipation <sup>4</sup>	$P_D$	0.15		W
Thermal Resistance from Junction to Ambient <sup>5</sup>	$R_{\theta JA}$	833		$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150		$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150		$^\circ\text{C}$

**MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted) NMOS:**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20V, V_{GS} = 0V$			1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 10V, V_{DS} = 0V$			$\pm 10$	$\mu A$
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.4	0.7	1.0	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 0.65A$		170	260	m $\Omega$
		$V_{GS} = 2.5V, I_D = 0.55A$		230	360	
		$V_{GS} = 1.8V, I_D = 0.45A$		330	590	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$		54.1		pF
Output Capacitance	$C_{oss}$			12.8		
Reverse Transfer Capacitance	$C_{rss}$			10.3		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		56		$\Omega$
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V, V_{GS} = 4.5V, I_D = 0.5A,$ $R_G = 10\Omega$		6.7		ns
Turn-on Rise Time	$t_r$			4.8		
Turn-off Delay Time	$t_{d(off)}$			17.3		
Turn-off Fall Time	$t_f$			7.4		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 0.5A$			1.2	V

**MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted) PMOS:**

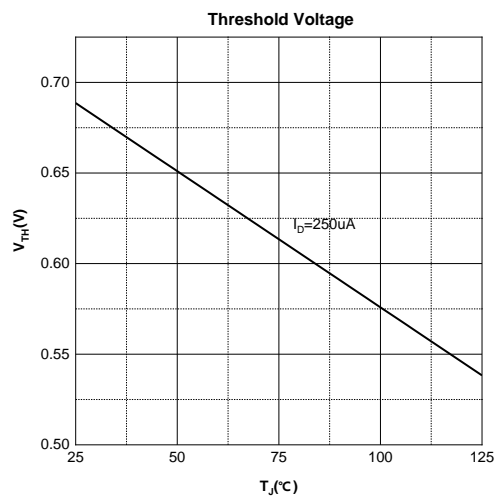
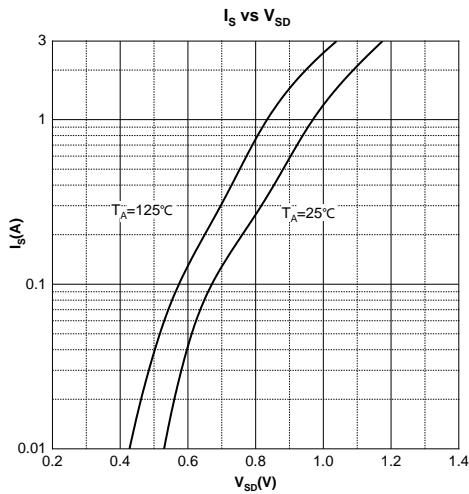
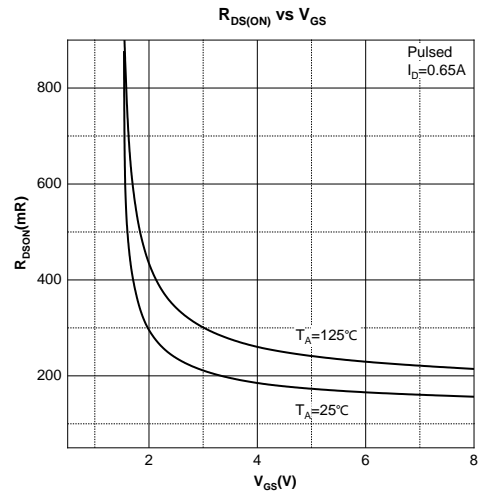
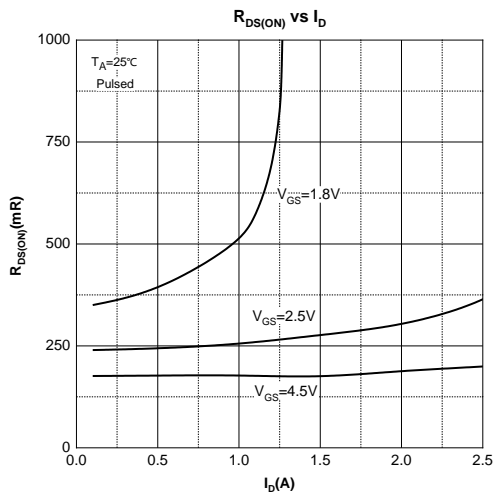
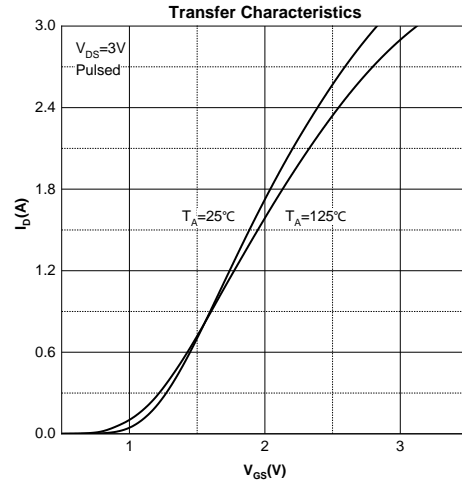
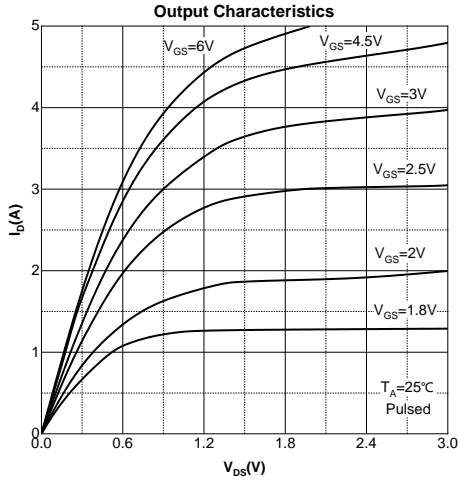
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -20V, V_{GS} = 0V$			-1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 10V, V_{DS} = 0V$			$\pm 10$	nA
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.4	-0.7	-1.0	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -1A$		400	580	m $\Omega$
		$V_{GS} = -2.5V, I_D = -0.8A$		570	840	
		$V_{GS} = -1.8V, I_D = -0.5A$		810	1140	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -10V, V_{GS} = 0V, f = 1MHz$		76		pF
Output Capacitance	$C_{oss}$			14.6		
Reverse Transfer Capacitance	$C_{rss}$			12.2		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		68		$\Omega$
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -10V, V_{GS} = -4.5V, I_D = -0.2A,$ $R_G = 10\Omega$		9		ns
Turn-on Rise Time	$t_r$			5.7		
Turn-off Delay Time	$t_{d(off)}$			32.6		
Turn-off Fall Time	$t_f$			20.3		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = -0.5A$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .
- 5.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

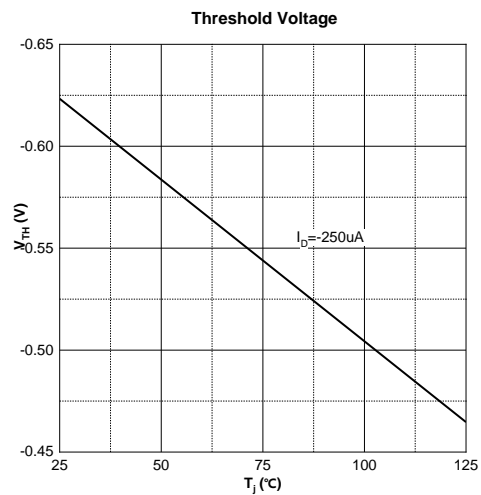
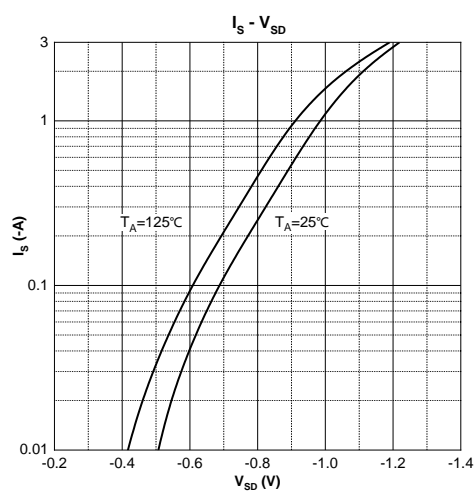
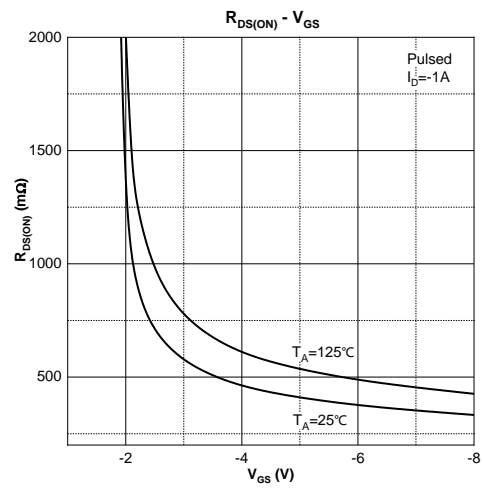
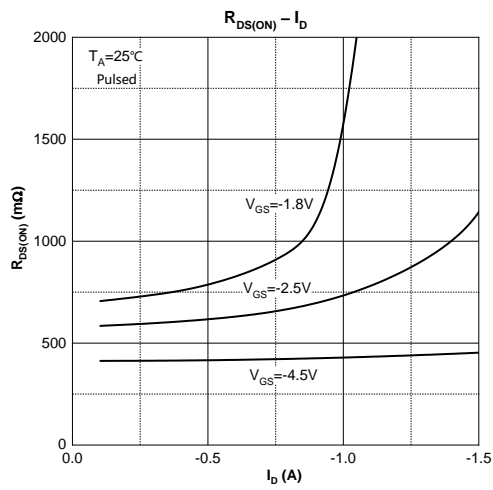
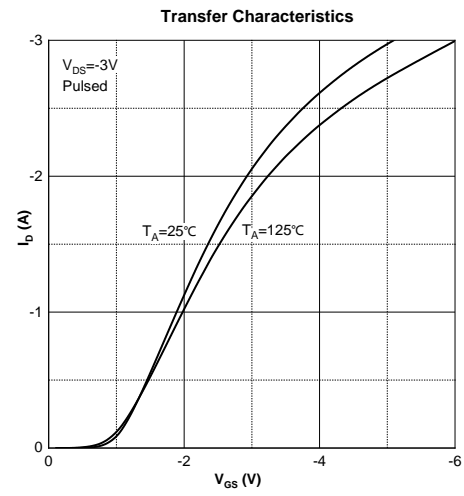
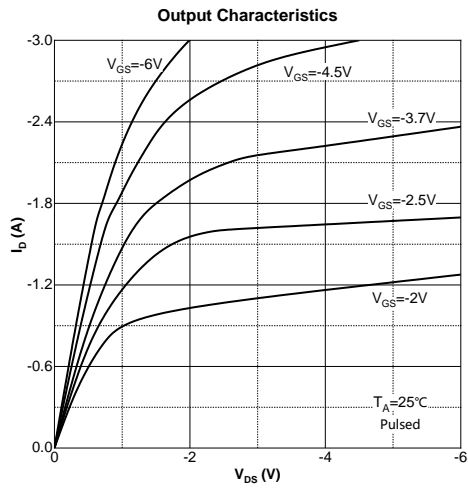
# Typical Characteristics

## NMOS:

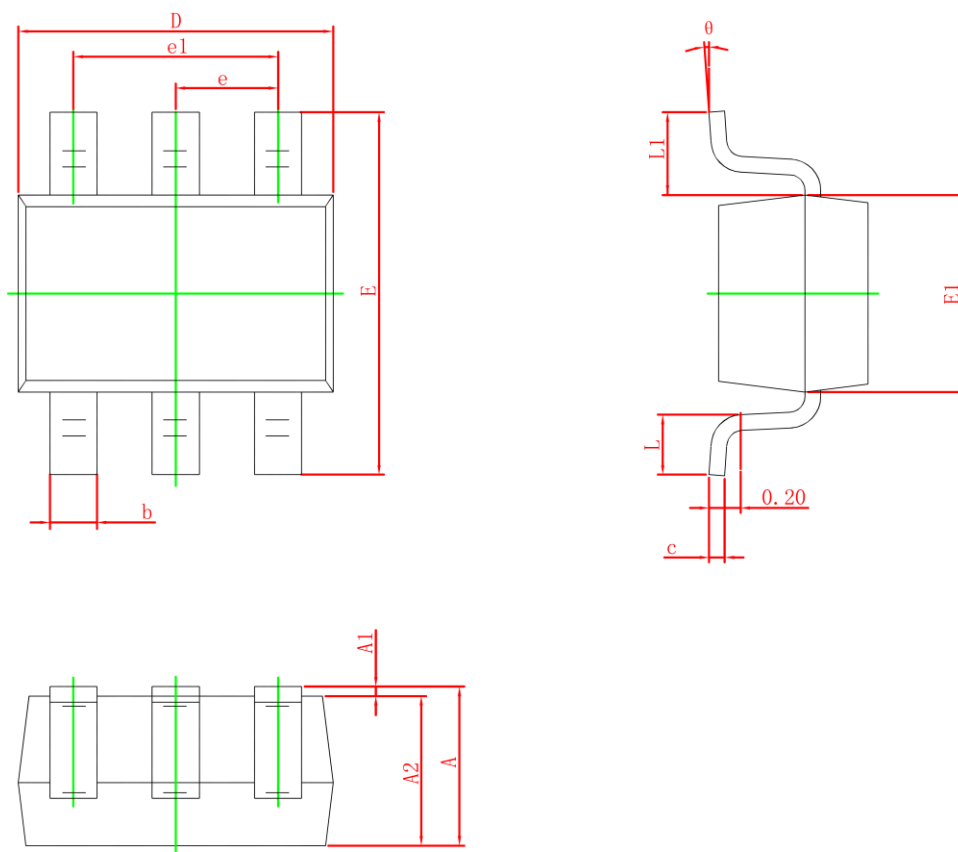


# Typical Characteristics

## PMOS:



## SOT-363 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A1	0	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D	1.800	2.200	0.071	0.087
E	2.000	2.450	0.079	0.096
E1	1.150	1.350	0.045	0.053
e	0.650TYP		0.026TYP	
e1	1.200	1.400	0.047	0.055
L1	0.525REF		0.021REF	
L	0.260	0.460	0.010	0.018
$\theta$	0°	8°	0°	8°